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SCHRITTWIESER(10) **Pub. No.: US 2022/0353997 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **COMPONENT CARRIER WITH EMBEDDED
COMPONENT CONNECTED BY GALVANIC
CONNECTION STACK****Publication Classification**(51) **Int. Cl.****H05K 1/18** (2006.01)**H05K 1/09** (2006.01)(52) **U.S. Cl.****CPC** **H05K 1/182** (2013.01); **H05K 1/09**
(2013.01)(71) Applicant: **AT&S Austria Technologie &
Systemtechnik Aktiengesellschaft,**
Leoben (AT)(72) Inventor: **Wolfgang SCHRITTWIESER,**
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ABSTRACT

A component carrier includes a layer body with at least one electrically conductive layer structure and/or at least one electrically insulating layer structure, a component embedded in the layer body, and at least one galvanic connection stack at least partially on at least part of at least one main surface of the layer body. At least one of a bottom main surface and a top main surface of the embedded component is electrically connected to the at least one galvanic connection stack.

